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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re: Application of:

Group Art Unit: 2826

Siddhartha Bhowmik, et al.

Examiner: Fazli Erdem

Serial No.: 09/967,094

Filed: September 28, 2001

Title: A BARRIER LAYER FOR INTERCONNECT
STRUCTURES OF A SEMICONDUCTOR
WAFER AND METHOD FOR DEPOSITING
THE BARRIER LAYER

Commissioner for Patents
Box Non-Fee Amendment
Washington, DC 20231

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TECHNOLOGY CENTER 2800

RESPONSE

The paper is submitted in response to the Office Action mailed on August 28, 2002, for which a response is due not later than November 28, 2002.

AMENDMENT

IN THE SPECIFICATION:

Please amend the specification as follows:

IN THE CLAIMS:

Please amend the claims as follows:

1. (Amended) [A] An interconnect structure, comprising:
 - (a) a substrate having disposed thereon a topographical structure including a dielectric material and a recess formed therein;